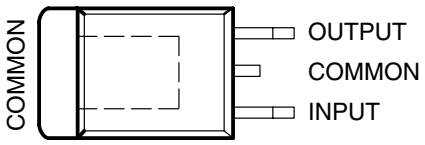
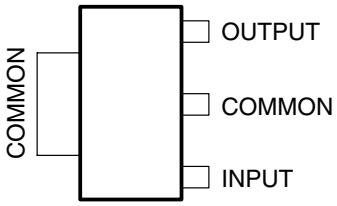
- **Qualified for Automotive Applications**
- **3-Terminal Regulators**
- **Output Current Up To 500 mA**
- **No External Components**
- **Internal Thermal-Overload Protection**
- **High Power-Dissipation Capability**
- **Internal Short-Circuit Current Limiting**
- **Output Transistor Safe-Area Compensation**

KTP PACKAGE
(TOP VIEW)



DCY (SOT-223) PACKAGE
(TOP VIEW)



description/ordering information

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents and also as the power-pass element in precision regulators.

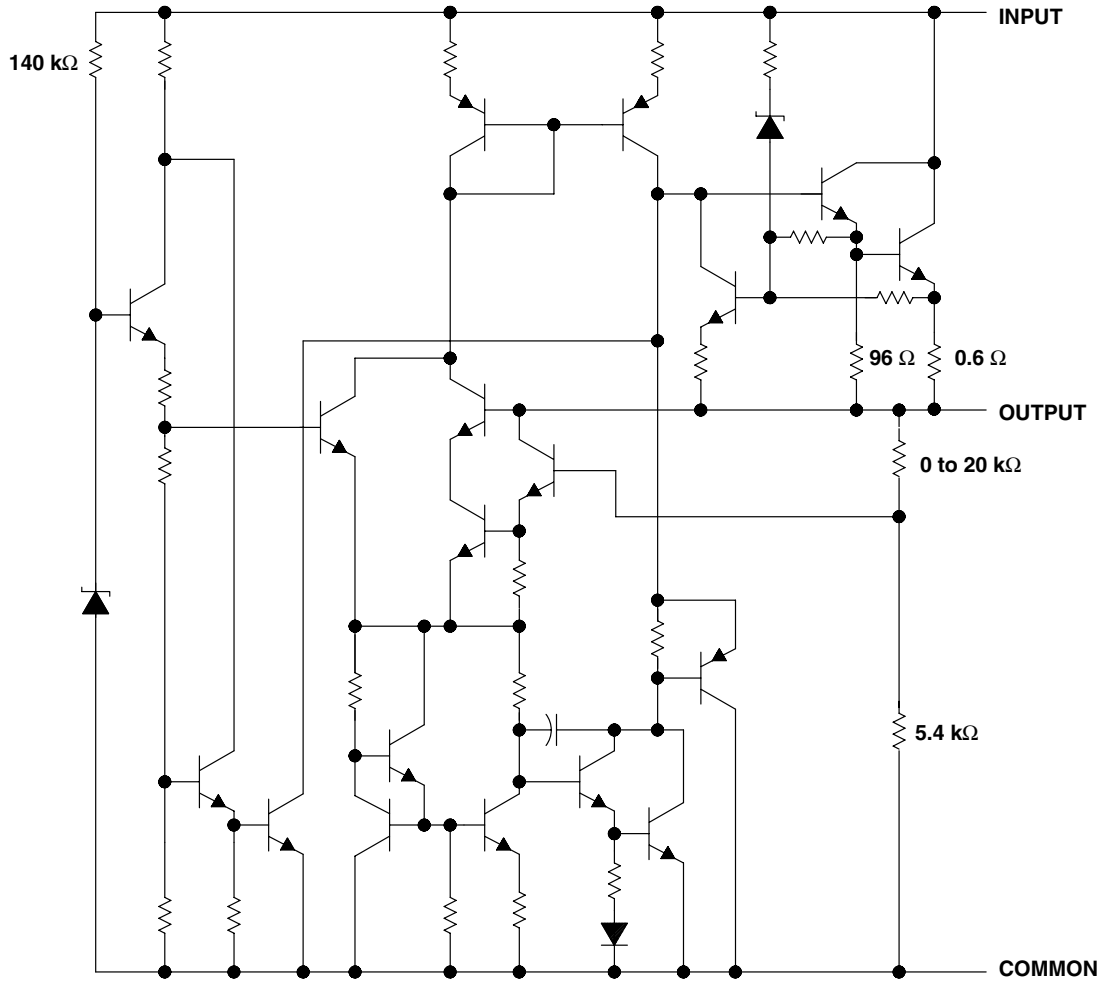
ORDERING INFORMATION†

T_J	V_O(NOM) (V)	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	3.3	PowerFLEX™ (KTP)	Reel of 3000	UA78M33QKTPRQ1	78M33CQ
		SOT-223 (DCY)	Reel of 2500	UA78M33QDCYRQ1	C3Q
	5	PowerFLEX™ (KTP)	Reel of 3000	UA78M05QKTPRQ1	78M05CQ
		SOT-223 (DCY)	Reel of 2500	UA78M05QDCYRQ1	C5Q
	8	PowerFLEX™ (KTP)	Reel of 3000	UA78M08QKTPRQ1	78M08CQ
		SOT-223 (DCY)	Reel of 2500	UA78M08QDCYRQ1	C8Q
	10	PowerFLEX™ (KTP)	Reel of 3000	UA78M10QKTPRQ1	78M10CQ

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

‡ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

schematic



Resistor values shown are nominal.

absolute maximum ratings over virtual junction temperature range (unless otherwise noted)†

Input voltage, V_I . . . . . 35 V
Operating virtual junction temperature, T_J . . . . . 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

package thermal data (see Note 1)

PACKAGE	BOARD	θ_{JC}	θ_{JA}
PowerFLEX (KTP)	High K, JESD 51-5	19°C/W	28°C/W
SOT-223 (DCY)	High K, JESD 51-7	4°C/W	53°C/W

NOTE 1: Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

recommended operating conditions

			MIN	MAX	UNIT
V_I	Input voltage	µA78M33	5.3	25	V
		µA78M05	7	25	
		µA78M06	8	25	
		µA78M08	10.5	25	
		µA78M09	11.5	26	
		µA78M10	12.5	28	
		µA78M12	14.5	30	
I_O	Output current			500	mA
T_J	Operating virtual junction temperature		–40	125	°C

electrical characteristics at specified virtual junction temperature, V_I = 8 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		μA78M33Q			UNIT
			MIN	TYP	MAX	
Output voltage‡	I_O = 5 mA to 350 mA, V_I = 8 V to 20 V		3.2	3.3	3.4	V
		T_J = –40°C to 125°C	3.1	3.3	3.5	
Input voltage regulation	I_O = 200 mA	V_I = 5.3 V to 25 V		9	100	mV
		V_I = 8 V to 25 V		3	50	
Ripple rejection	V_I = 8 V to 18 V, f = 120 Hz	I_O = 100 mA, T_J = –40°C to 125°C	62			dB
		I_O = 300 mA	62	80		
Output voltage regulation	V_I = 8 V,	I_O = 5 mA to 500 mA		20	100	mV
Temperature coefficient of output voltage	I_O = 5 mA,	T_J = –40°C to 125°C		–1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV
Dropout voltage				2		V
Bias current				4.5	6	mA
Bias current change	I_O = 200 mA, T_J = –40°C to 125°C	V_I = 8 V to 25 V,			0.8	mA
	I_O = 5 mA to 350 mA,	T_J = –40°C to 125°C			0.5	
Short-circuit output current	V_I = 35 V			300		mA
Peak output current				700		mA

† All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.
‡ This specification applies only for dc power dissipation permitted by absolute maximum ratings.

electrical characteristics at specified virtual junction temperature, V_I = 10 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		μA78M05Q			UNIT
			MIN	TYP	MAX	
Output voltage	I_O = 5 mA to 350 mA, V_I = 7 V to 20 V		4.8	5	5.2	V
		T_J = –40°C to 125°C	4.75		5.25	
Input voltage regulation	I_O = 200 mA	V_I = 7 V to 25 V		3	100	mV
		V_I = 8 V to 25 V		1	50	
Ripple rejection	V_I = 8 V to 18 V, f = 120 Hz	I_O = 100 mA, T_J = –40°C to 125°C	62			dB
		I_O = 300 mA	62	80		
Output voltage regulation	I_O = 5 mA to 500 mA			20	100	mV
	I_O = 5 mA to 200 mA			10	50	
Temperature coefficient of output voltage	I_O = 5 mA,	T_J = –40°C to 125°C		–1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV
Dropout voltage				2		V
Bias current				4.5	6	mA
Bias current change	I_O = 200 mA, T_J = –40°C to 125°C	V_I = 8 V to 25 V,			0.8	mA
	I_O = 5 mA to 350 mA,	T_J = –40°C to 125°C			0.5	
Short-circuit output current	V_I = 35 V			300		mA
Peak output current				0.7		A

† All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

electrical characteristics at specified virtual junction temperature, V_I = 14 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			μA78M08Q			UNIT
				MIN	TYP	MAX	
Output voltage	V_I = 10.5 V to 23 V,	I_O = 5 mA to 350 mA		7.7	8	8.3	V
			T_J = –40°C to 125°C	7.6		8.4	
Input voltage regulation	I_O = 200 mA	V_I = 10.5 V to 25 V			6	100	mV
		V_I = 11 V to 25 V			2	50	
Ripple rejection	V_I = 11.5 V to 21.5 V, f = 120 Hz	I_O = 100 mA,	T_J = –40°C to 125°C	56			dB
		I_O = 300 mA		56	80		
Output voltage regulation	I_O = 5 mA to 500 mA				25	160	mV
	I_O = 5 mA to 200 mA				10	80	
Temperature coefficient of output voltage	I_O = 5 mA,	T_J = –40°C to 125°C			–1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				52		μV
Dropout voltage					2		V
Bias current					4.6	6	mA
Bias current change	V_I = 10.5 V to 25 V,	I_O = 200 mA,	T_J = –40°C to 125°C			0.8	mA
	I_O = 5 mA to 350 mA,	T_J = –40°C to 125°C				0.5	
Short-circuit output current	V_I = 35 V				250		mA
Peak output current					0.7		A

† All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

electrical characteristics at specified virtual junction temperature, V_I = 17 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			μA78M10Q			UNIT
				MIN	TYP	MAX	
Output voltage	V_I = 12.5 V to 25 V,	I_O = 5 mA to 350 mA		9.6	10	10.4	V
			T_J = –40°C to 125°C	9.5		10.5	
Input voltage regulation	I_O = 200 mA	V_I = 12.5 V to 28 V			7	100	mV
		V_I = 14 V to 28 V			2	50	
Ripple rejection	V_I = 15 V to 25 V, f = 120 Hz	I_O = 100 mA,	T_J = –40°C to 125°C	59			dB
		I_O = 300 mA		55	80		
Output voltage regulation	I_O = 5 mA to 500 mA				25	200	mV
	I_O = 5 mA to 200 mA				10	100	
Temperature coefficient of output voltage	I_O = 5 mA,	T_J = –40°C to 125°C			–1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				64		μV
Dropout voltage					2		V
Bias current					4.7	6	mA
Bias current change	V_I = 12.5 V to 28 V,	I_O = 200 mA,	T_J = –40°C to 125°C			0.8	mA
	I_O = 5 mA to 350 mA,	T_J = –40°C to 125°C				0.5	
Short-circuit output current	V_I = 35 V				245		mA
Peak output current					0.7		A

† All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UA78M05QDCYRG4Q1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C5Q	Samples
UA78M05QDCYRQ1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C5Q	Samples
UA78M33QDCYRG4Q1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C3Q	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UA78M05-Q1, UA78M33-Q1 :

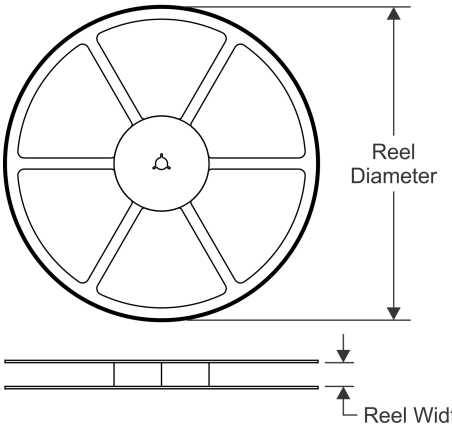
- Catalog: UA78M05, UA78M33

NOTE: Qualified Version Definitions:

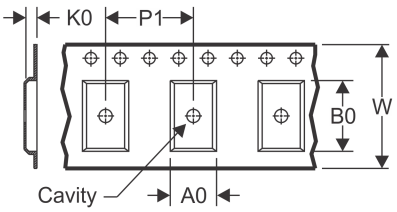
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

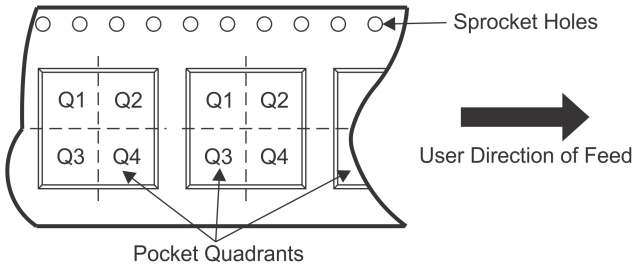


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

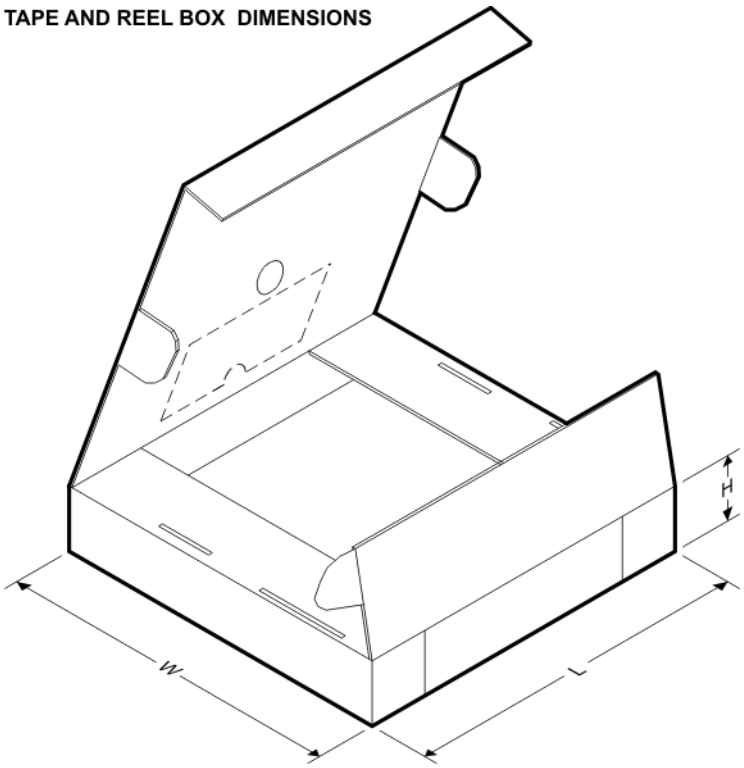
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA78M05QDCYRG4Q1	SOT-223	DCY	4	2500	330.0	12.4	6.8	7.3	1.88	8.0	12.0	Q3
UA78M33QDCYRG4Q1	SOT-223	DCY	4	2500	330.0	12.4	6.83	7.42	1.88	8.0	12.0	Q3

TAPE AND REEL BOX DIMENSIONS

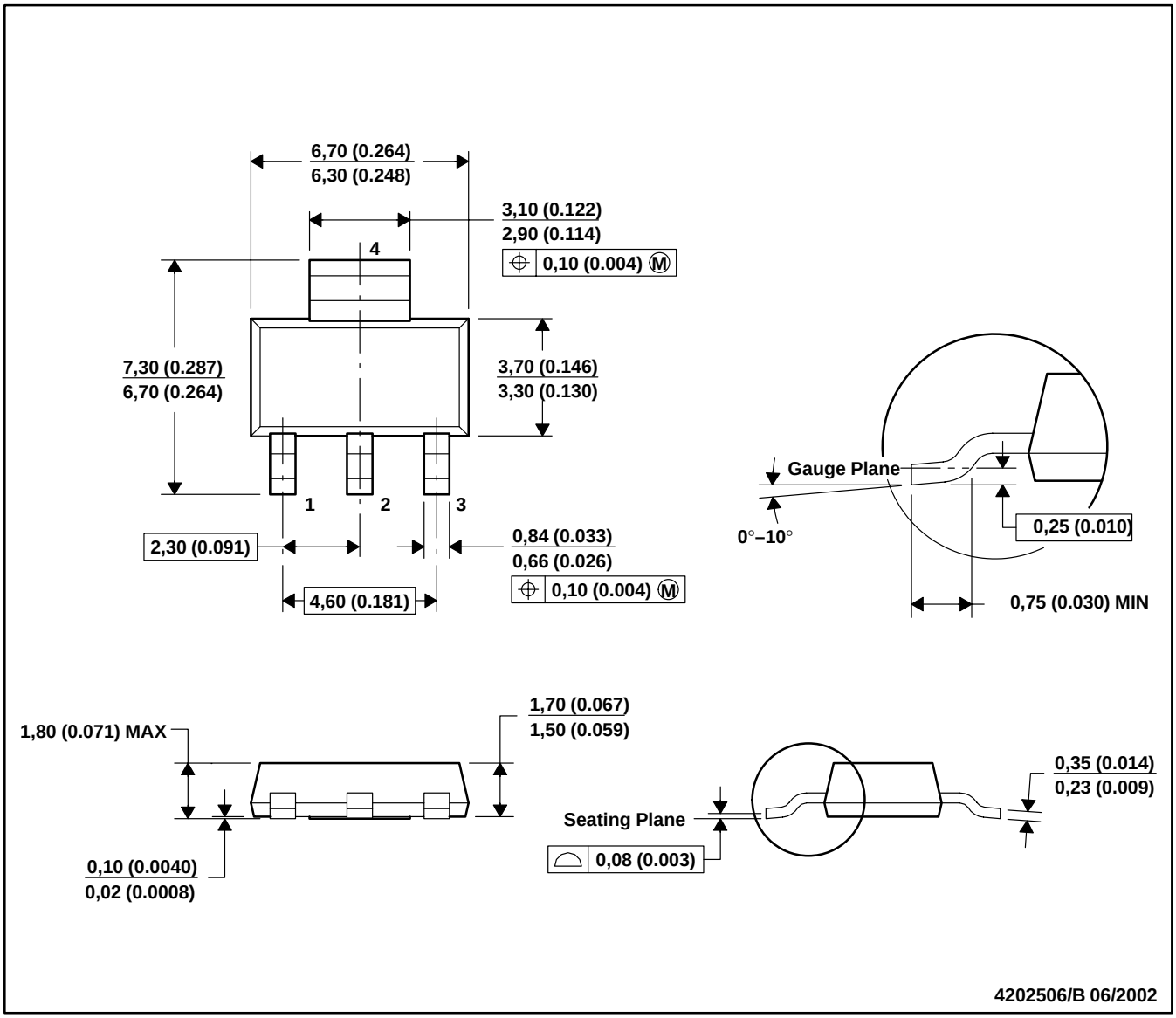


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA78M05QDCYRG4Q1	SOT-223	DCY	4	2500	346.0	346.0	29.0
UA78M33QDCYRG4Q1	SOT-223	DCY	4	2500	346.0	346.0	29.0

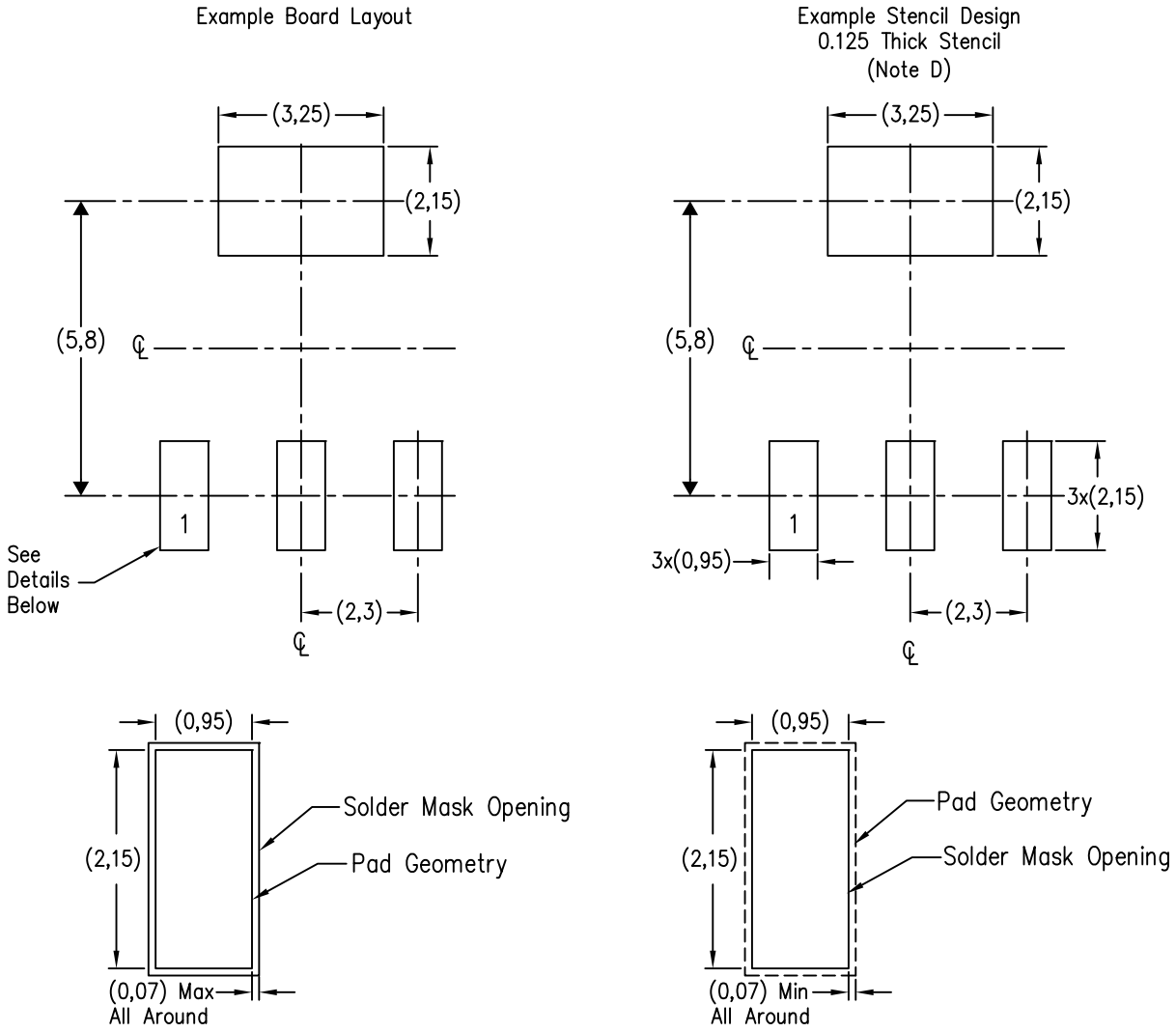
MPDS094A – APRIL 2001 – REVISED JUNE 2002

DCY (R-PDSO-G4) **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters (inches).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC TO-261 Variation AA.

DCY (R–PDSO–G4) PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil recommendations. Refer to IPC 7525 for stencil design considerations.

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